

30 April 2003

09/762,582

| L Number | Hits | Search Text | DB | Time stamp |
|----------|-------|---|---|---------------------|
| - | 0 | 762582.apn. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 11:23 |
| - | 9 | ((("5116430") or ("3716462") or ("3930963"))).PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 13:53 |
| - | 1 | jp-51149131-\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 12:13 |
| - | 2 | 4163705.pn. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 12:13 |
| - | 7 | ((("5849171") or ("4430173") or ("5433840"))).PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 09:43 |
| - | 2657 | 204/198,212,232,242,273,275.1.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 13:55 |
| - | 773 | 204/224r.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 13:55 |
| - | 3270 | 204/198,212,232,242,273,275.1.ccls. 204/224r.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 13:55 |
| - | 35 | (204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.) and electroless and (electrolytic or electroplating) and robot | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:04 |
| - | 58753 | 204/\$.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:04 |
| - | 55 | 204/\$.ccls. and electroless and (electrolytic or electroplating) and robot | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:04 |
| - | 20 | (204/\$.ccls. and electroless and (electrolytic or electroplating) and robot) not ((204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.) and electroless and (electrolytic or electroplating) and robot) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:14 |
| - | 2 | 6080291.pn. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:07 |

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|---|-----|---|---|---------------------|
| - | 813 | 204/\$.ccls. and (robot or robotic) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:14 |
| - | 78 | (204/\$.ccls. and (robot or robotic)) and electroless | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:15 |
| - | 81 | 204/\$.ccls. and electroless and (robot or robotic or (transfer adj unit) or (transfer adj device) or (transfer adj arm)) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:16 |
| - | 26 | (204/\$.ccls. and electroless and (robot or robotic or (transfer adj unit) or (transfer adj device) or (transfer adj arm))) not (204/\$.ccls. and electroless and (electrolytic or electroplating) and robot) not ((204/\$.ccls. and electroless and (electrolytic or electroplating) and robot) not ((204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.) and electroless and (electrolytic or electroplating) and robot)) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:17 |
| - | 26 | (204/\$.ccls. and electroless and (robot or robotic or (transfer adj unit) or (transfer adj device) or (transfer adj arm))) not (204/\$.ccls. and electroless and (electrolytic or electroplating) and robot) not ((204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.) and electroless and (electrolytic or electroplating) and robot) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:33 |
| - | 2 | 6197181.pn. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:21 |
| - | 2 | jp-56158424-\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:34 |
| - | 1 | 1982-04830E.NRAN. | DERWENT | 2003/04/29 14:33 |
| - | 2 | jp-05311496-\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:35 |
| - | 2 | jp-07193214-\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:37 |
| - | 1 | 1995-217803.NRAN. | DERWENT | 2003/04/29 14:37 |
| - | 2 | jp-02000341-\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:39 |
| - | 1 | 1990-047945.NRAN. | DERWENT | 2003/04/29 14:39 |

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|---|-------|--|---|---------------------|
| - | 2 | jp-56161221-\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:42 |
| - | 1 | jp-51149131-\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:43 |
| - | 1 | 1976-75692X.NRAN. | DERWENT | 2003/04/29 14:42 |
| - | 2 | jp-03146698-\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:44 |
| - | 2 | jp-05098500-\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:45 |
| - | 2 | jp-62235499-\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:46 |
| - | 2 | jp-63026400-\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:50 |
| - | 1 | 1997wo-??22733.ap.prai. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:51 |
| - | 0 | wo-22733-\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:52 |
| - | 0 | wo-00022733-\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:52 |
| - | 0 | wo-97022733-\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 14:52 |
| - | 58753 | 204/\$.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 15:10 |
| - | 708 | 204/\$.ccls. and (electroless and (electrolytic or electroplating or electroplate)) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 15:11 |
| - | 82 | (204/\$.ccls. and (electroless and (electrolytic or electroplating or electroplate))) and (robot or robotic or ((transfer or conveyance or conveyor) adj (means! or unit or device or system or arm))) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 15:12 |

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|---|--------|---|---|---------------------|
| - | 160054 | 205/\$.ccls. or 427/\$.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 15:47 |
| - | 14963 | (205/\$.ccls. or 427/\$.ccls.) and (semiconductor or wafer) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 15:48 |
| - | 759 | ((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or wafer)) and electroless and (electroplating or electroplated or electroplate or electrolytic or electrochemically) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 15:49 |
| - | 54 | ((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or wafer)) and (electroless near2 (tank or bath)) and ((electroplating or electroplated or electroplate or electrolytic or electrochemically) near2 (tank or bath)) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 15:49 |
| - | 60 | ((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or wafer)) and (electroless near2 (tank or bath or chamber)) and ((electroplating or electroplated or electroplate or electrolytic or electrochemically) near2 (tank or bath or chamber)) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 15:54 |
| - | 7 | ((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or wafer)) and (electroless near2 (tank or bath or chamber)) and ((electroplating or electroplated or electroplate or electrolytic or electrochemically) near2 (tank or bath or chamber))) and (robot or robotic or ((transfer or conveyor or conveyance) near (arm or unit or device or means!))) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 15:51 |
| - | 29 | ((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or wafer)) and (electroless near2 (tank or bath or chamber)) and ((electroplating or electroplated or electroplate or electrolytic or electrochemically) near2 (tank or bath or chamber))) and ((copper adj sulfate) or "Cuso.sub.4") | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/29 15:55 |
| - | 8 | ("5500315" or ("5310580" or ("5389496" or ("5139818"))).PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 08:52 |
| - | 0 | electroless and ((copper adj sulfate) or "cuso.sub.4") and ((chlorine or chloride) adj ions) and (sulfuric adj acid) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 08:54 |
| - | 1896 | electroless and ((copper adj sulfate) or "cuso.sub.4") | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 08:54 |
| - | 1019 | (electroless and ((copper adj sulfate) or "cuso.sub.4")) and (sulfuric adj acid) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 08:54 |

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|---|-------|---|---|---------------------|
| - | 220 | ((electroless and ((copper adj sulfate) or "cuso.sub.4")) and (sulfuric adj acid)) and (((polyethylene or polypropylene) adj glycol) or peg! or ppg!) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 08:55 |
| - | 52 | (((electroless and ((copper adj sulfate) or "cuso.sub.4")) and (sulfuric adj acid)) and (((polyethylene or polypropylene) adj glycol) or peg! or ppg!)) and sulfur and nitrogen | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 08:55 |
| - | 51 | (((electroless and ((copper adj sulfate) or "cuso.sub.4")) and (sulfuric adj acid)) and (((polyethylene or polypropylene) adj glycol) or peg! or ppg!)) and sulfur and nitrogen) and (chlorine or chloride) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 09:06 |
| - | 0 | uk-1222969-\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 09:07 |
| - | 1 | gb-1222969-\$.did. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 09:11 |
| - | 59 | (204/\$.ccls. or 205/\$.ccls.) and bubble and (pressure near (module or modulation or modulating or pulse or pulsating or pulsed or pulsing or pulsated or varied or variable or cyclical)) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 10:01 |
| - | 8 | (204/\$.ccls. or 205/\$.ccls.) and (bubble with (pressure near (module or modulation or modulating or pulse or pulsating or pulsed or pulsing or pulsated or varied or variable or cyclical))) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 10:09 |
| - | 111 | (204/\$.ccls. or 205/\$.ccls.) and ((bubble or gas) same (pressure near (module or modulation or modulating or pulse or pulsating or pulsed or pulsing or pulsated or varied or variable or cyclical))) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 10:20 |
| - | 102 | (204/\$.ccls. or 205/\$.ccls.) and ((bubble or gas) same (pressure near (modulate or modulation or modulating or pulse or pulsating or pulsed or pulsing or pulsated or varied or variable or cyclical))) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 13:38 |
| - | 21529 | (204/\$.ccls. or 205/\$.ccls.) and (semiconductor or wafer or microelectronic or (integrated adj circuit) or (circuit board)) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 10:19 |
| - | 2051 | ((204/\$.ccls. or 205/\$.ccls.) and (semiconductor or wafer or microelectronic or (integrated adj circuit) or (circuit board))) and bubble | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 10:19 |
| - | 241 | ((204/\$.ccls. or 205/\$.ccls.) and (semiconductor or wafer or microelectronic or (integrated adj circuit) or (circuit board))) and (bubble with pressure) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 10:20 |

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|---|-------|--|---|---------------------|
| - | 69 | ((204/\$.ccls. or 205/\$.ccls.) and (semiconductor or wafer or microelectronic or (integrated adj circuit) or (circuit board))) and ((bubble or gas) same (pressure near (modulate or modulation or modulating or pulse or pulsating or pulsed or pulsing or pulsated or varied or variable or cyclical))) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 10:21 |
| - | 2 | 5865894.pn. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 13:41 |
| - | 83136 | 204/\$.ccls. or 205/\$.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 13:41 |
| - | 18 | (204/\$.ccls. or 205/\$.ccls.) and (semiconductor) and (bubbles with (sonic or ultrasonic or megasonic)) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 13:45 |
| - | 2 | ((204/\$.ccls. or 205/\$.ccls.) and (semiconductor) and (bubbles with (sonic or ultrasonic or megasonic))) and (hermetically or sealed) | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 13:45 |
| - | 10914 | 204/198,212,232,242,273,275.1.ccls. 204/224r.ccls. 205/88,98,122,123,125,148,157,183,184,187,261,291.ccls. 427/96,98,443.1.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 14:07 |
| - | 1933 | (204/198,212,232,242,273,275.1.ccls. 204/224r.ccls. 205/88,98,122,123,125,148,157,183,184,187,261,291.ccls. 427/96,98,443.1.ccls.) and semiconductor | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 14:07 |
| - | 506 | ((204/198,212,232,242,273,275.1.ccls. 204/224r.ccls. 205/88,98,122,123,125,148,157,183,184,187,261,291.ccls. 427/96,98,443.1.ccls.) and semiconductor) and | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 14:07 |
| - | 135 | ((204/198,212,232,242,273,275.1.ccls. 204/224r.ccls. 205/88,98,122,123,125,148,157,183,184,187,261,291.ccls. 427/96,98,443.1.ccls.) and semiconductor) and electroless) and ((copper adj (sulfate or sulphate)) or | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 14:08 |
| - | 61 | ((204/198,212,232,242,273,275.1.ccls. 204/224r.ccls. 205/88,98,122,123,125,148,157,183,184,187,261,291.ccls. 427/96,98,443.1.ccls.) and semiconductor) and electroless) and ((copper adj (sulfate or sulphate)) or | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 14:11 |
| - | 18 | ((204/198,212,232,242,273,275.1.ccls. 204/224r.ccls. 205/88,98,122,123,125,148,157,183,184,187,261,291.ccls. 427/96,98,443.1.ccls.) and semiconductor) and electroless) and ((copper adj (sulfate or sulphate)) or | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 14:12 |
| - | 2 | ((204/198,212,232,242,273,275.1.ccls. 204/224r.ccls. 205/88,98,122,123,125,148,157,183,184,187,261,291.ccls. 427/96,98,443.1.ccls.) and semiconductor) and electroless) and ((copper adj (sulfate or sulphate)) or | USPAT; US-PGPUB; EPO; JPO; DERWENT | 2003/04/30 14:12 |

"cuso-sub.4") and hermetically